Figure 1: Proposed Chlorination/Ligand Addition Mechanism for Au ALE using SO<sub>2</sub>Cl<sub>2</sub>/PEt<sub>3</sub>

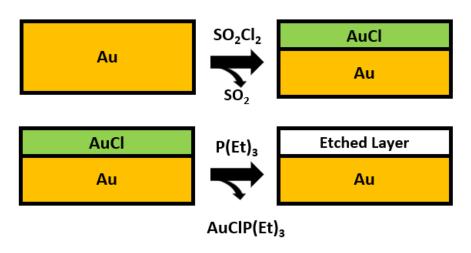


Figure 3: AuCl(PEt<sub>3</sub>) etch product during PEt3 exposure on Au at 150°C matches expected isotopic ratios

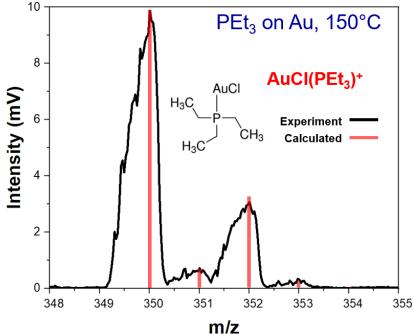


Figure 2: ALE of Au QCM at 150 °C with etch rate of 0.63 Å/cycle

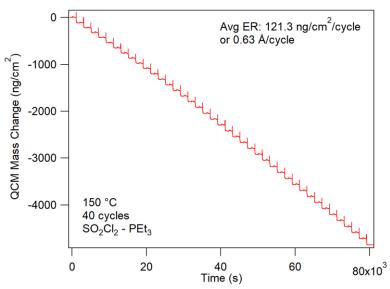


Figure 4: Cu<sub>2</sub>Cl<sub>2</sub>(PEt<sub>3</sub>)<sub>2</sub> etch product observed during PEt<sub>3</sub> exposure on Cu at 150°C

